## History of Computing.....The first computer



## The Babbage <br> Difference Engine (1832) <br> 25,000 parts cost: £17,470

A mechanical digital calculator...

Mechanical computing devices
Used decimal number system
Could perform basic arithmetic operations

Even store and execute

Problem: Too complex and expensive!

## Further Reading....

- http://en.wikipedia.org/wiki/Difference engine
- How Computers Do Math
(ISBN: 0471732788) Wiley, Clive Maxfield and Alvin Brown.


## ENIAC - The first electronic computer (1946)



Vacuum tube based computer...

For Military applications...

80 ft long, 8.5 ft high, several ft wide...

With ~18,000 vacuum tubes!

Problem: Reliability issues and excessive power consumption! ${ }_{4}$

## Parts of the ORACLE Computer-Oak Ridge Automatic Computer and Logical Engine---Oak Ridge National Lab (1950-54)

Used vacuum tubes, transistors, and diodes.

Addition time: 70 microseconds Multiplication time: 370-590 microseconds Division time: 590 microseconds

These times include the storage access time, which was about 62 microseconds.

Credit: Deutsches Museum, Munich, Germany

## The Transistor Revolution...

http://www.nobelprize.org/educational/physics/integrated_circuit/history/

The first point contact transistor
William Shockley, John Bardeen, and Walter Brattain Bell Laboratories, Murray Hill, New Jersey (1947)


First transistor
Bell Labs, 1947
(Ge point contactBipolar transistor )
Bardeen and
Brattian
-Nobel Laureates
BJT (1948)
Schockley

- Nobel Laureate

General Electric types G11 and G11A commercial point contact transistors


Transistor Size (1/8" OD X 3/8")

## The First Integrated Circuits



ECL 3-input Gate Motorola 1966

Jack Kilby, Texas Instruments (1958), the first integrated circuit, (Ge based) or microchip (patent \#3,138,743), Nobel Prize in 2000


Robert Noyce (1927-1990), co-founder of Fairchild and Intel, the first monolithic integrated circuit, (U.S. Patent 2,981,877 July 1959). Si based with Cu interconnects, more practical than Kilby's IC.

Bipolar logic - built with BJTs Early 1960's (TTL, ECL)
TTLs offered higher integration density-composed largest fraction of semiconductor market until the 1980s

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## Integrated Circuits (Early) History

- Invention of BJT (1948)
- First silicon transistor (1954)
- MOS transistor (1960)
$\square$ MOS integrated circuit (1962)
- DRAM cell (1968)
- Intel formed (1968) (Intel: short form of integrated electronics)
- AMD formed (1969)
$\square$ Microprocessor invented (1971)
- 32-bit microprocessors (1980)


## For more historical perspectives....



Chapter 11
VLSI Technology and Circuits by K. Banerjee and S. Ikeda

## BJT vs FETs

## Both are based on basic properties of pn junctions

- A Bipolar Junction Transistor (BJT) is a 3 terminal device
- Uses the injection of minority carriers (under a forward bias)
- A BJT is a "bipolar" device (both electrons are holes are involved in its operation)
- It is an asymmetric device....why?
- A Field Effect Transistor (FET) is also a 3 terminal device (plus a substrate terminal)
- A FET is a "unipolar" device (majority carrier only)
- It is based on controlling the depletion width of a--- junction (JFET) or a Schottky Barrier (MESFET) through a control (gate) voltage

Power has been the main driver for various technologies.....vacuum tubes, BJT, PMOS, NMOS, CMOS.....???

## Recalling the BJT.



Schematic cross-sectional view of a planar NPN bipolar junction transistor...emitter is more heavily doped than collector....depth of " $p$ " region must be smaller than the diffusion length of electrons


Basic structure of an NPN BJT


Schematic symbols for PNP and NPN type BJTs
$>$ Both electrons and holes are involved in the operation.....hence the name "bipolar"
$>$ For NPN BJT: electrons are injected from a high-concentration emitter ( $\mathrm{n}+\mathrm{+}$ ) into the p-type base.....where they are minority carriers that diffuse toward the collector ( $\mathrm{n}+$ ).....hence BJTs are minority-carrier devices
$>$ Quiescent power (drawn even in idle circuits) due to small base current limits largescale integration

## Other FETs

- If the metal gate electrode is separated from the semiconductor by an insulator- metal-insulatorsemiconductor FET (MISFET)
- Also called an IGFET (insulated gateFET)
- Most commonly called as MOSFET (metal-oxidesemiconductor FET)
- FETs have high input impedance-since the control voltage is applied to a reverse biased junction or Schottky Barrier or across an insulator-----they are better suited (than BJTs) for controlled switching between conducting (ON) and non-conducting (OFF) states---therefore better for digital circuit implementation....low-power
- FETs are also more integrable...processing perspective


## Strange History of FETs.....

- Actually FET was invented (proposed) in 1925!! (by Julius Lilienfeld)
- But.....it never worked....Why?.....
- Role of surface defects....dangling bonds etc. causing large number of surface states....Fermi level pinning
- Silicon dioxide....a key material for Silicon's success.....
- Bardeen and Brattain accidentally discovered the first (bipolar) transistor: the Ge point contact transistor---while trying to experimentally demonstrate the FET
- First MOSFET demonstrated in 1960 by Kahng and Atalla at Bell Labs
- First logic gates using MOSFETs (both n-type and ptype...thus Complementary-MOS-FET)— Frank Wanlass at Fairchild in 1963


## Intel 4004 Micro-Processor



# Nov 1971 <br> ~2300 transistors <br> Max. CPU Clk rate: 750 KHz <br> PMOS only (10 um process) 

Note: although NMOS was conceived in the early 1960sapplication in wrist watches and portable electronics (of 1960s)--but device quality was poor, hence PMOS was used until 1974

The 19714004 Microprocessor (10 um process) was PMOS only
---Intel 8080 (8-bit) Microprocessor (1974)
6 thousand transistors, 2 MHz
NMOS only (6 um process)

## Intel Pentium (IV) Microprocessor



## 2003: <br> CMOS based <br> $>50$ million transistors <br> > 3GHz operation

## Economic Implications



FIG 1.1 Size of worldwide semiconductor market
Source: Semiconductor Industry Association.
For more up to date info. go to the International Technology Roadmap for semiconductors (ITRS) http://public.itrs.net/

## Moore's Law

- In 1965, Gordon Moore (co-founder of Intel) noted that the number of transistors on a chip doubled every 18 to 24 months
$\square$ He made a prediction that semiconductor technology will double its effectiveness every 18 (24) months


## Moore's Law



Electronics, April 19, 1965.

## Evolution in Complexity



Lecture 2, ECE 122A, VLSI Principles

## IC Classification

- Circuit size (transistor count)
- Circuit technology (BJT, BiCMOS, NMOS, CMOS)
- Design style
- standard cell
- gate array
- custom
- Size classification (historical)

| - $<100$ | SSI | 1963 |
| :--- | :--- | :--- |
| - $100-3000$ | MSI | 1970 |
| - $3000-30,000$ | LSI | 1975 |
| - $30,000-1,000000$ VLSI | 1980 |  |
| - $>1,000000$ | ULSI | 1990 |
| - $>1$ billion | GSI | 2010 |

## Transistor Counts



Lecture 2, ECE 122A, VLSI Principles
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## Moore's Law in Microprocessors



Transistors on Lead Microprocessors double every 2 years

## Die Size Growth



Courtesy, Intel

Die size grows by $14 \%$ to satisfy Moore's Law

## Frequency



Lead Microprocessors frequency doubles every 2 years

## Power Dissipation



Courtesy, Intel

Lead Microprocessor power continues to increase

## Power is a major problem....



Power delivery and dissipation will be prohibitive

## Power density



Power density too high to keep junctions at low temp

- Technology shrinks by 0.7/generation
- With every generation can integrate $2 x$ more functions per chip; chip cost does not increase significantly (Dennard's (IBM) scaling lawtransistors become faster, consume less power and become cheaper)
$\square$ Cost of a function decreases by $2 x$
a But ...
- How to design chips with more and more functions?
- Design engineering population does not double every two years...
- Hence, a need for more efficient design methods
- Exploit different levels of abstraction


## Design Abstraction Levels



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## Silicon and Dopant Atoms


(b)

Free carriers are electrons

(c)

Free carriers are holes

FIG 1.6 Silicon lattice and dopant atoms

Atomic number of Si: 14
Eighth most abundant element on earth!! Electronic configuration: $[1 s]^{2}[2 s]^{2}[2 p]^{6}[3 s]^{2}[3 p]^{2}$

## Pn-junction Diode



Forward Bias:
connect Vdd to p-type and GND to n-type (current flows)

Reverse Bias: connect Vdd to n-type and GND to p-type (no current)

## Anode Cathode



## FIG 1.7 <br> p-n junction diode structure and symbol

## MOS Transistor is like a tap....



Think about how you want your tap to function....

# MOS (Metal-Oxide-Semiconductor) Transistor 



FIG 1.8 nMOS transistor (a) and pMOS transistor (b)
Gate controls the flow of charge from source to drain.....
Vt is the minimum voltage (threshold voltage) required to turn ON transistors

## MOS Transistor as a Switch



FIG 1.9 Transistor symbols and switch-level models

## Inverter (NOT Gate)



## Transistor Level Implementation


(a)
(b)

FIG 1.10 Inverter schematic (a) and symbol (b) $Y=\bar{A}$


FIG 1.21 Bad noninverting buffer

## MOS voltage levels

## Case 1: NMOS discharges capacitor

- Initially: Vout = Vcc (capacitor fully charged)
- $\mathrm{V}_{\mathrm{GS}}$ of NMOS = Vcc
- What is final Vout?


- NMOS remains on since $V_{G S}>V_{T}$
- Final output voltage $\mathrm{V}_{\text {out }}=0 \mathrm{~V}$
- Value at source $(=0)$ is transferred to the drain (output)....completely


## MOS voltage levels

## Case 2: NMOS charges capacitor

- Initially: Vout = 0
- Initial $\mathrm{V}_{\mathrm{GS}}$ of NMOS = Vcc
- What is final Vout?


- NMOS remains on until $\mathrm{V}_{\mathrm{GS}}=\mathrm{V}_{\mathrm{T}}$
- Final output voltage $\mathrm{V}_{\text {out }}=\mathrm{V}_{\mathrm{cc}}-\mathrm{V}_{\mathrm{T}}$
- Value at drain (=1) not transferred completely to the source (output).. 39


## MOS voltage levels

Repeat for PMOS:

- Case 1: PMOS discharging capacitor

- PMOS on until $\mathrm{V}_{\mathrm{GS}}=-\mathrm{V}_{\mathrm{T}}$
- $\mathrm{V}_{\text {out }}=\left|\mathrm{V}_{\mathrm{T}}\right|$

Value at drain (=0) is not transferred completely to the source (output)...

- Case 2: PMOS charging capacitor

- PMOS always on $\left(\mathrm{V}_{\mathrm{GS}}=-\mathrm{V}_{\mathrm{CC}}\right)$
- $\mathrm{V}_{\text {out }}=\mathrm{V}_{\mathrm{CC}}$

Value at source (=1) is transferred to the drain (output)....completely

## MOS voltage levels

- NMOS summary
- Transfers logic '0’ completely (good for discharging a node)
- Does not transfer logic '1' completely (bad for charging a node)
- PMOS summary
- Transfers logic '1’ completely
- Does not transfer logic ' 0 ' completely
- Result:
- NMOS used for pull-down, PMOS for pull-up


## Switch Behavior of NMOS and PMOS


b
(a)

b
(b)

(c)

(d)


OFF


ON


OFF

ON


ON

ON
ON


ON OFF




To establish a path between "a" and "b", at least g1 OR g2 must be ON

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## 2-input NAND Gate

Table 1.2 NAND gate truth table


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## CMOS NAND Implementation

Recall De Morgan's Law.....

$Y=\overline{A \cdot B}=\bar{A}+\bar{B}$

(a)
(b)

FIG 1.11 -input NAND gate schematic (a) and symbol (b) $\mathrm{Y}=\overline{\mathrm{A} \bullet \mathrm{B}}$

Also, 2-input NOR: $Y=\overline{A+B}=\bar{A} \cdot \bar{B}$

## CMOS 3-input NAND Implementation



FIG 1.12 3-input NAND gate schematic $Y=\overline{A \bullet B \bullet C}$
$Y=0$, when $A=B=C=1$
Hence, $A, B, C$ are in series for the NMOS (pull-down network)

## $Y=1$, when $A$ or $B$ or $C=0$

Hence, $A, B, C$ are in parallel for the PMOS (pullup network)


## FIG 1.22 Various implementations of a CMOS 4-input AND gate

